## **Amendment to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

## **Listing of Claims:**

- 1. (Currently Amended) An aqueous polymer dispersion, obtained by
  - a) preparing an aqueous polychloroprene dispersion with a gel content of 0.1 wt.% 30 wt.%, based on the polymer, prepared by polymerization of chloroprene in an aqueous emulsion at 0°C 70°C 10°C 25°C of chloroprene and at pH value of 10-14 and, optionally, ethylenically unsaturated monomers which can be copolymerized with chloroprene and
  - b) subsequently storing the dispersion at temperatures of from 50°C 110°C until the gel content has risen by at least 10 wt.% to 1 60 wt.%, based on the polymer,

wherein the aqueous polymer dispersion does not have a significant drop in pH after storage.

- 2. (Original) Aqueous polymer dispersion according to Claim 1, characterized in that the polychloroprene dispersion has a particle diameter of 60 to 120 nm.
- 3. (Original) The aqueous polymer dispersion according to Claim 1, wherein the regulator content is preferably 0 to 0.25 mmol, based on 100 g of monomer.
- 4. (Cancelled)
- 5. (Original) The aqueous polymer dispersion according to Claim 1, wherein the dispersion has a gel content of 0.5 5 wt.% before the conditioning.

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- 6. (Original) The aqueous polymer dispersion according to Claim 1, wherein the storage of the dispersion takes place at 60°C to 90°C.
- 7. (Original) The aqueous polymer dispersion according to Claim 1, wherein after the conditioning in b) the polychloroprene dispersion has a gel content of 5 to 30 wt.%.
- 8. (Withdrawn) A method of preparing adhesive formulations comprising adding one or more auxiliaries and/or additives selected from the group consisting of fillers, wetting agents, zinc oxide, organic thickeners, inorganic thickeners, fungicides, tackifying resins, and organic solvents to the polymer dispersion according to Claim 1.
- 9. (Withdrawn) An adhesive formulation comprising the aqueous polymer dispersion according to Claim 1.
- 10. (Withdrawn) Substrates coated with adhesive formulations according to Claim 9.
- 11. (Withdrawn) The method of Claim 8, wherein the fillers are selected from the group consisting of quartz flour, quartz sand, highly disperse silica, barite, calcium carbonate, chalk, dolomite and talcum.
- 12. (Withdrawn) The method of Claim 8, wherein the wetting agents are selected from the group consisting of polyphosphates, naphthalenesulfonic acid, ammonium polyacrylate salts and sodium polyacrylate salts.
- 13. (Withdrawn) The method of Claim 8, wherein the organic thickeners are selected from the group consisting of cellulose derivatives, alginates, starch, starch derivatives and polyacrylic acid.

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- 14. (Withdrawn) The method of Claim 8, wherein the inorganic thickeners include bentonites.
- 15. (Withdrawn) The method of Claim 8, wherein the fungicides are selected from the group consisting of phenol derivatives, cresol derivatives, and organotin compounds.
- 16. (Withdrawn) The method of Claim 8, wherein the tackifying resins are selected from the group consisting colophony ester, phthalate resins, and alkylphenol resins with softening points above 110°C.
- 17. (Withdrawn) The method of Claim 8, wherein the organic solvents are selected from the group consisting of toluene, xylene, butyl acetate, methyl ethyl ketone, ethyl acetate, dioxane and mixtures thereof.
- 18. (Withdrawn) The adhesive formulation of Claim 9, comprising one or more auxiliaries and/or additives selected from the group consisting of fillers, wetting agents, zinc oxide, organic thickeners, inorganic thickeners, fungicides, tackifying resins, and organic solvents.
- 19. (Withdrawn) The adhesive formulation of Claim 18, wherein the fillers are selected from the group consisting of quartz flour, quartz sand, highly disperse silica, barite, calcium carbonate, chalk, dolomite and talcum.
- 20. (Withdrawn) The adhesive formulation of Claim 18, wherein the wetting agents are selected from the group consisting of polyphosphates, naphthalenesulfonic acid, ammonium polyacrylate salts and sodium polyacrylate salts.

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- 21. (Withdrawn) The adhesive formulation of Claim 18, wherein the organic thickeners are selected from the group consisting of cellulose derivatives, alginates, starch, starch derivatives and polyacrylic acid.
- 22. (Withdrawn) The adhesive formulation of Claim 18, wherein the inorganic thickeners include bentonites.
- 23. (Withdrawn) The adhesive formulation of Claim 18, wherein the fungicides are selected from the group consisting of phenol derivatives, cresol derivatives, and organotin compounds.
- 24. (Withdrawn) The adhesive formulation of Claim 18, wherein the tackifying resins are selected from the group consisting colophony ester, phthalate resins, and alkylphenol resins with softening points above 110°C.
- 25. (Withdrawn) The adhesive formulation of Claim 18, wherein the organic solvents are selected from the group consisting of toluene, xylene, butyl acetate, methyl ethyl ketone, ethyl acetate, dioxane and mixtures thereof.

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